

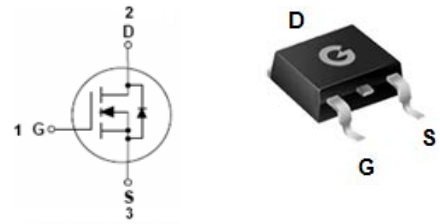
Features

- High switching speed

HF

Mechanical Data

- Case: TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



TO-252

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL4N50D	TO-252	80 pcs / Tube & 2500 pcs / Tape & Reel	4N50D

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	500	V
Gate-to-Source Voltage	V _{GSS}	±30	V
Continuous Drain Current	I _D	4	A
Pulsed Drain Current	I _{DM}	16	A

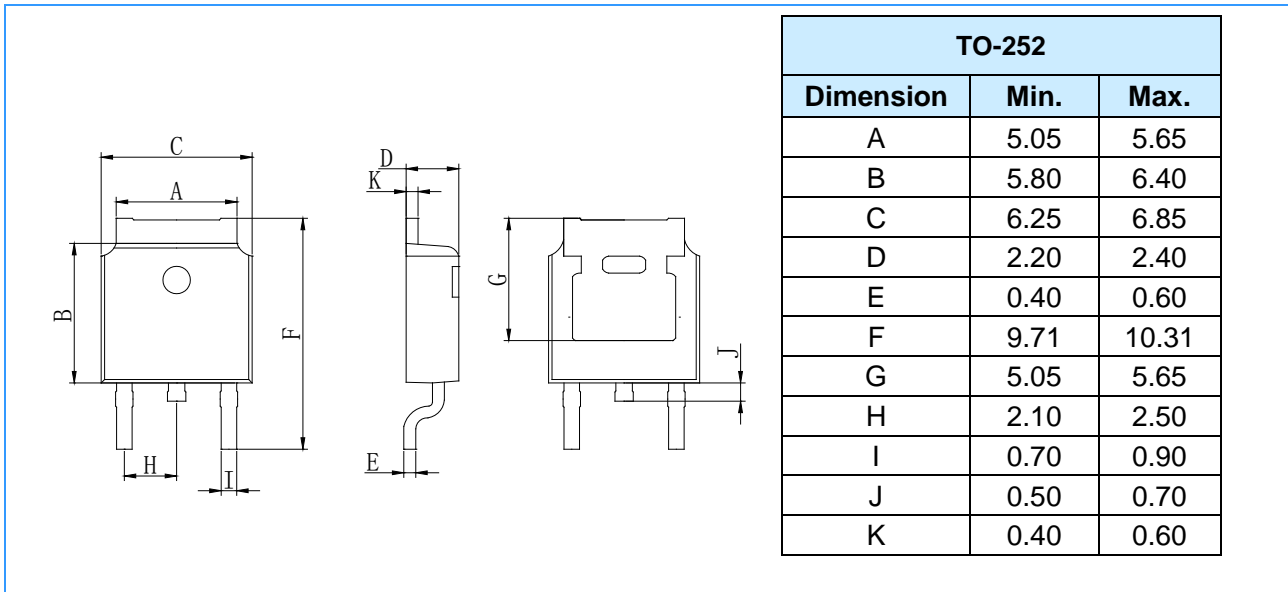
Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation (T _C = 25°C)	P _D	83	W
Thermal Resistance Junction-to-Case	R _{θJC}	1.5	°C/W
Thermal Resistance Junction-to-Air	R _{θJA}	62.5	°C/W
Operating Junction Temperature Range	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

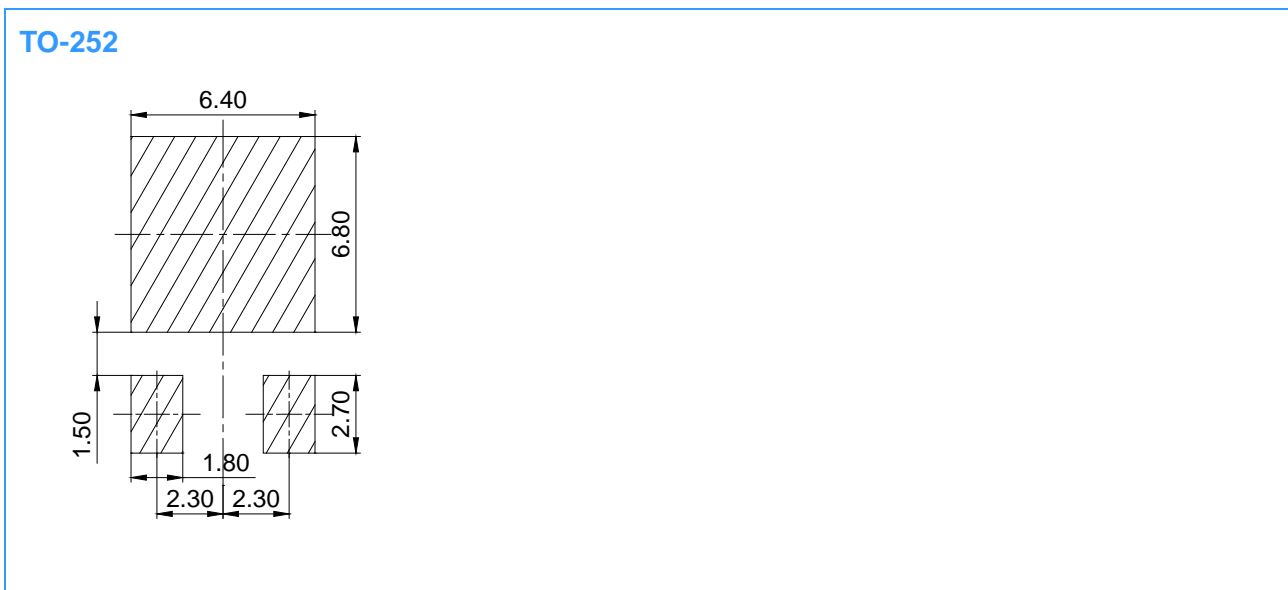
Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500V, V_{GS} = 0V$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Static Drain-Source On-resistance	$V_{GS} = 10V, I_D = 2A$	-	-	2	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{GS} = 0V$	-	485	-	pF
C_{OSS}	Output Capacitance	$V_{DS} = 25V$	-	65	-	
C_{RSS}	Reverse Transfer Capacitance	$f = 1.0\text{MHz}$	-	5	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD} = 250V$ $R_G = 25\Omega$ $I_D = 4A$	-	14	-	ns
t_r	Turn-on Rise Time		-	21	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	27	-	
t_f	Turn-Off Fall Time		-	20	-	
Q_G	Total Gate-Charge	$V_{DD} = 400V$	-	11	-	nC
Q_{GS}	Gate to Source Charge	$V_{GS} = 10V$	-	3	-	
Q_{GD}	Gate to Drain (Miller) Charge	$I_D = 4A$	-	5	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage	$I_{SD} = 4A, V_{GS} = 0V$	-	-	1.6	V
I_{SD}	Diode Continuous Forward Current		-	-	4	A
I_{SM}	Diode Pulsed Forward Current		-	-	16	A
t_{rr}	Body Diode Reverse Recovery Time	$V_{GS} = 0V, I_S = 4A$ $di/dt = 100A/\mu s$	-	36	-	nS
Q_{rr}	Body Diode Reverse Recovery Charge		-	33	-	μC

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)



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